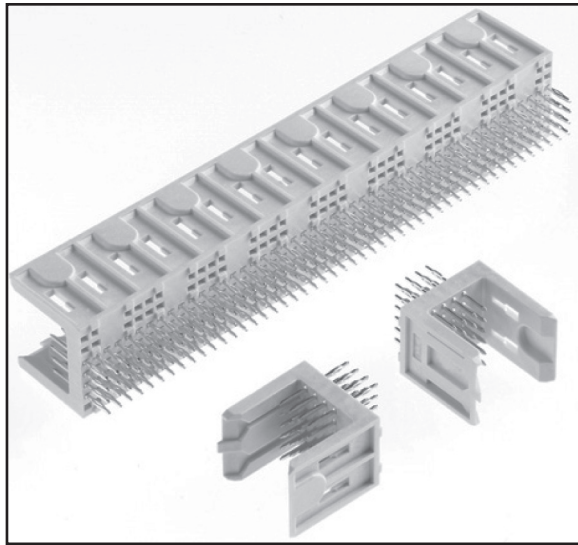


# 3M™ MetPak™ 2-FB Header

2 mm 4/5 Row, Vertical, Solder or Press-Fit Tail, Shouldered Pin

MP2 Series



## Solder Tail

- End-to-end stackable
- Select load capability
- Monoblockable
- Shoulder Pin

## Press Fit

- End-to-end stackable
- Early mate late break for hot swapping (press-fit EMLB adjusted by application tooling)
- Select load capability
- Monoblockable
- Push-on shoulder pin
- Optional feed-through tail for rear plug-up midplane applications
- Accepts Universal Tooling
- RoHS Compliant. See the Regulatory Information Appendix (RIA) in the “RoHS compliance” section of [www.3Mconnectors.com](http://www.3Mconnectors.com) for compliance information (RIA E1 & C1 apply)

Date Modified: September 17, 2013

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## Physical

### Insulation:

Material: High Temp LCP  
Flammability: UL 94V-0  
Color: Beige

### Contact:

Material: Phosphor Bronze

### Plating:

Underplating: 50  $\mu$ " [1.27  $\mu$ m] Nickel  
Wiping Area: See Ordering Information  
Solder Tails: See Ordering Information

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## Electrical

**Current Rating:** Signal: 1.5 A – All contacts simultaneously

**Insulation Resistance:** 10<sup>3</sup> M $\Omega$

**Withstanding Voltage:** 1,000 V<sub>AC</sub>

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## Environmental

**Temperature Rating:** -55°C to +125°C

**Process Temperature Rating:** 260°C (Profile per J-STD-020C)

**Moisture Sensitivity Level:** 1 (per J-STD-020C)

UL File No.: E68080

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**3M**

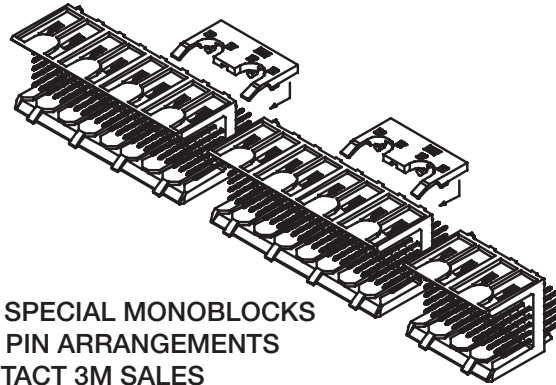
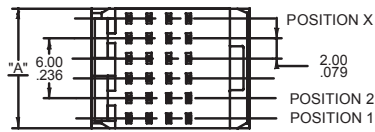
Electronic Solutions Division  
Interconnect Solutions  
<http://www.3Mconnectors.com>

3M is a trademark of 3M Company.  
For technical, sales or ordering information call  
**800-225-5373**

# 3M™ MetPak™ 2-FB Header

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MP2 Series



FOR SPECIAL MONOBLOCKS  
AND PIN ARRANGEMENTS  
CONTACT 3M SALES  
REPRESENTATIVE



**4 ROW PRODUCT**

mm [inch]			
Tolerance Unless Noted			
	0	0.0	0.00
mm	±3	±0.3	±0.13

[ ] Dimensions for  
Reference Only



**5 ROW PRODUCT**



**SOLDER TAIL  
PRODUCT**



**PRESS FIT  
PRODUCT**



**PRESS FIT  
PRODUCT  
REAR  
PLUG-UP**

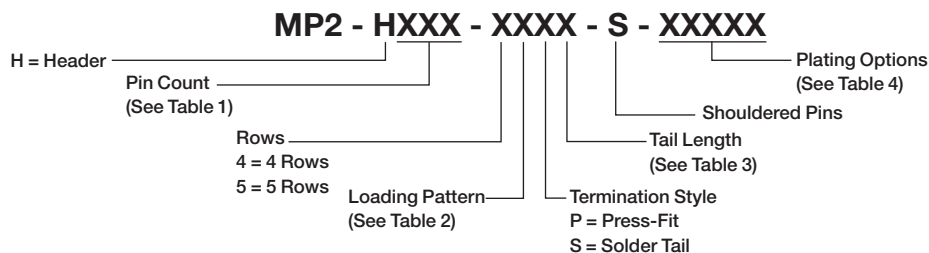
Contact 3M For Rear Plug-Up Option



**Notes:**

1. Refer to IEC 61076-4-104 Futurebus+® global standard.
2. "Press Fit" describes a contact tail having a compliant section designed to make a reliable electrical connection with a plated through-hole (PTH) in a printed circuit board, typically a "back plane."

## Ordering Information



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# 3M™ MetPak™ 2-FB Header

2 mm 4/5 Row, Vertical, Solder or Press-Fit Tail, Shouldered Pin

MP2 Series

Pin Count	Dim. "A" mm [inch]	Dim "C" mm [inch]	Rows
024	11.95 [0.471]	10.00 [0.394]	4
048	23.95 [0.943]	22.00 [0.866]	4
072	35.95 [1.415]	34.00 [1.339]	4
096	47.95 [1.889]	46.00 [1.811]	4
120	59.95 [2.36]	58.00 [2.283]	4
144	71.95 [2.833]	70.00 [2.756]	4
168	83.95 [3.305]	82.00 [3.228]	4
192	95.95 [3.778]	94.00 [3.701]	4
030	11.95 [0.471]	10.00 [0.394]	5
060	23.95 [0.943]	22.00 [0.866]	5
090	35.95 [1.415]	34.00 [1.339]	5
120	47.95 [1.888]	46.00 [1.811]	5
150	59.95 [2.361]	58.00 [2.283]	5
180	71.95 [2.833]	70.00 [2.756]	5
210	83.95 [3.305]	82.00 [3.228]	5
240	95.95 [3.778]	94.00 [3.701]	5

Plating Suffix	Press-Fit Tails*	Solder Tails	Plating Composition
KR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.76 µm [30 µ"] Min. Au Contact Area 2.54 µm [100 µ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 µm [50 µ"] Min. Ni all over
LR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.08 µm [3 µ"] Min. Au Contact Area 0.67 µm [27 µ"] Min. PdNi Contact Area 2.54 µm [100 µ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 µm [50 µ"] Min. Ni all over
KV for rear plug-up only	(RIA E1 & C1 apply)		0.76 µm [30 µ"] Min. Au Primary Contact Area 0.10 µm [4 µ"] Min. Au Needle Eye Area 0.10 µm [4 µ"] Min. Au Secondary Contact Area 1.27 m [50 µ"] Min. Ni all over

Plating Suffix		Dim. "B"
Solder Tail	Press-Fit* Tail	
1	1	4.60 [0.181]
3		2.72 [0.107]

\*Compliant-Pin Tail

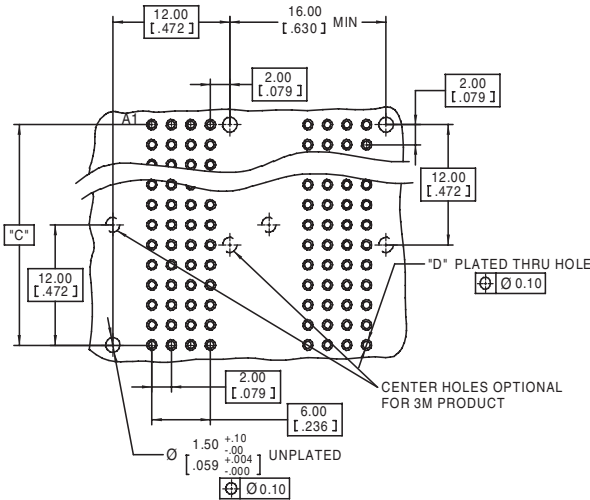
Loading Pattern Code	Description	Mate length Row A	Mate length Row B	Mate length Row C	Mate length Row D	Mate length Row E (5-Row Prod. Only)
1	All Positions Filled	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]
2	All Positions Filled	6.50 [0.256]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]
3	All Positions Filled	6.50 [0.256]	5.75 [0.226]	5.75 [0.226]	6.50 [0.256]	6.50 [0.256]
4	All Positions Filled	6.50 [0.256]	6.50 [0.256]	6.50 [0.256]	6.50 [0.256]	6.50 [0.256]
5	All Positions Filled	5.75 [0.226]	7.25 [0.285]	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]
6	All Positions Filled	7.25 [0.285]	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]
7	All Positions Filled	6.50 [0.256]	5.75 [0.226]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]
8	All Positions Filled	6.50 [0.256]	5.00 [0.197]	6.50 [0.256]	6.50 [0.256]	6.50 [0.256]
9	All Positions Filled	5.00 [0.197]	6.50 [0.256]	5.00 [0.197]	5.00 [0.197]	5.00 [0.197]
A	All Positions Filled	5.00 [0.197]	5.75 [0.226]	6.50 [0.256]	5.75 [0.226]	5.00 [0.197]
B	All Positions Filled	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]	5.75 [0.226]
C	All Positions Filled	5.00 [0.197]	5.00 [0.197]	6.50 [0.256]	5.00 [0.197]	5.00 [0.197]
D	All Positions Filled	5.75 [0.226]	5.75 [0.226]	7.25 [0.285]	5.75 [0.226]	5.75 [0.226]
E	All Positions Filled	7.25 [0.285]	7.25 [0.285]	7.25 [0.285]	7.25 [0.285]	7.25 [0.285]
G	All Positions Filled	7.25 [0.285]	5.75 [0.226]	5.75 [0.226]	5.00 [0.197]	5.00 [0.197]
H	All Positions Filled	5.00 [0.197]	5.75 [0.226]	5.75 [0.226]	7.25 [0.285]	7.25 [0.285]
J	All Positions Filled	8.00 [0.315]	8.00 [0.315]	8.00 [0.315]	8.00 [0.315]	8.00 [0.315]
K	All Positions Filled	5.00 [0.197]	6.50 [0.256]	7.25 [0.285]	6.50 [0.256]	5.00 [0.197]

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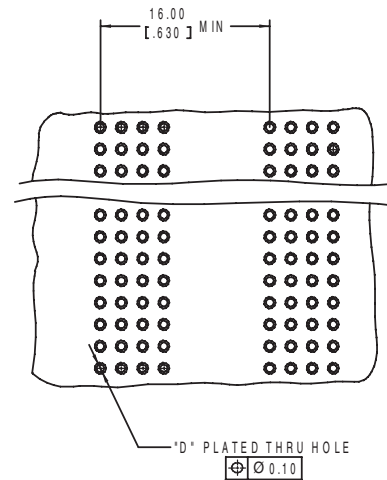
# 3M™ MetPak™ 2-FB Header

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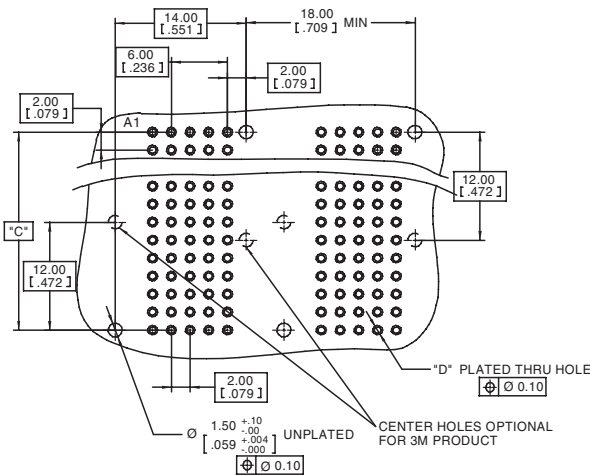
**RECOMMENDED 4 ROW SOLDER  
TAIL PCB HOLE MOUNTING PATTERN**



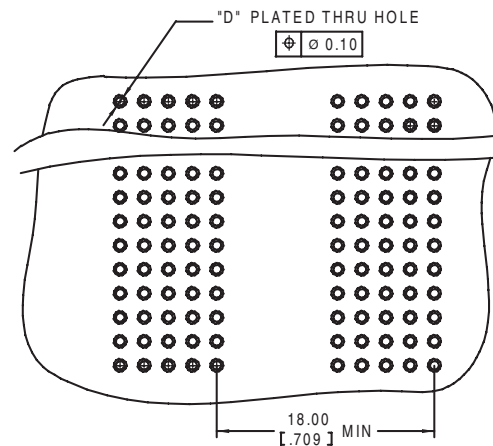
**RECOMMENDED 4 ROW PRESS-FIT  
PCB HOLE MOUNTING PATTERN**

**Table 5 - HOLE PLATING FINISHES**

HOLE	Finished Dia. MM [in]	Immersion Matte Sn Thickness microns [μ"]	Electrolytic Au Thickness microns [μ"]	OSP ENTEK Thickness microns [μ"]	Drilled Hole Dia. mm [in]
"D"	0.700-0.800 [.0276-.0315]	0.025-0.045 [0.001-0.002]	0.1 - 0.5 [4 - 20]	0.2 - 0.5 [8 - 20]	0.830-0.860 [.0330-.0340] or 0.85 mm [#66] TWIST DRILL



**RECOMMENDED 5 ROW SOLDER  
TAIL PCB HOLE MOUNTING PATTERN**



**RECOMMENDED 5 ROW PRESS-FIT  
PCB HOLE MOUNTING PATTERN**

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